

AM27S19, 'S19A, 'LS19, 'LS19SA

256-Bit (32x8) Bipolar PROM

The AM27S19 (32 words by 8 bits) is a Schottky TTL Programmable Read-Only Memory (PROM).

This device is available in three-state (AM27S19) output versions. These outputs are compatible with low-power Schottky bus standards capable of satisfying the requirements of a variety of microprogrammable controls, mapping functions, code conversions, or logic replacements. Easy word depth expansion is facilitated by an active LOW output enable (\overline{G}).

Rochester Electronics Manufactured Components

Rochester branded components are manufactured using either die/wafers purchased from the original suppliers or Rochester wafers recreated from the original IP. All recreations are done with the approval of the OCM.

Parts are tested using original factory test programs or Rochester developed test solutions to guarantee product meets or exceeds the OCM data sheet.

Quality Overview

- ISO-9001
- AS9120 certification
- Qualified Manufacturers List (QML) MIL-PRF-38535
 - Class Q Military
 - Class V Space Level
- Qualified Suppliers List of Distributors (QSLD)
 - Rochester is a critical supplier to DLA and meets all industry and DLA standards.

Rochester Electronics, LLC is committed to supplying products that satisfy customer expectations for quality and are equal to those originally supplied by industry manufacturers.

The original manufacturer's datasheet accompanying this document reflects the performance and specifications of the Rochester manufactured version of this device. Rochester Electronics guarantees the performance of its semiconductor products to the original OEM specifications. 'Typical' values are for reference purposes only. Certain minimum or maximum ratings may be based on product characterization, design, simulation, or sample testing.

Am27S19/27S19A Am27S19SA/27LS19

256-Bit (32x8) Bipolar PROM



DISTINCTIVE CHARACTERISTICS

- Ultra high speed
- Highly reliable, ultra-fast programming Platinum-Silicide fuses
- · High-programming yield

- Low-current PNP inputs
- · High-current open collector and three-state outputs
- · Fast chip select

GENERAL DESCRIPTION

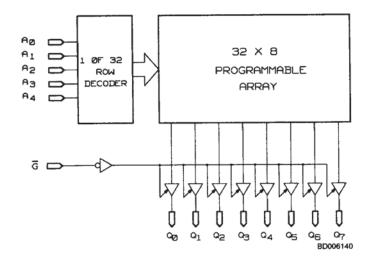
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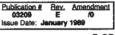
This device is also available in a low-power version Am27LS19.

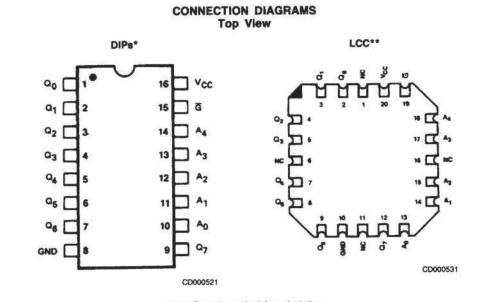
BLOCK DIAGRAM



PRODUCT SELECTOR GUIDE

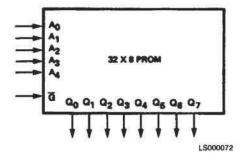
Three-State Part Number	Am27S19SA		Am27S19A		Am27S19		Am27LS19	
Address Access Time	15 ns	20 ns	25 ns	35 ns	40 ns	50 ns	55 ns	70 ns
Operating Range	с	м	с	м	с	м	с	м





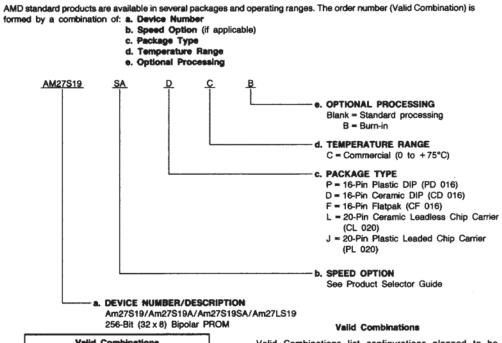
Note: Pin 1 is marked for orientation. *Also available in a 16-pin Flatpack. Pinout identical to DIPs. **Also available in a 16-pin Plastic Leaded Chip Carrier. Pinout identical to LCC.

LOGIC SYMBOL



ORDERING INFORMATION

Standard Products



Valid Com	binations
AM27S19	PC, PCB,
AM27S19A	DC, DCB, FC, FCB,
AM27S19SA	LC, LCB,
AM27LS19	JC, JCB

Valid Combinations list configurations planned to be supported in volume for this device. Consult the local AMD sales office to confirm availability of specific valid combinations, to check on newly released combinations, and to obtain additional data on AMD's standard military grade products.

MILITARY ORDERING INFORMATION

APL Products

AMD products for Aerospace and Defense applications are available in several packages and operating ranges. APL (Approved Products List) products are fully compliant with MIL-STD-883C requirements. The order number (Valid Combination) for APL products is formed by a combination of: a. Device Number b. Speed Option (if applicable) c. Device Class d. Package Type e. Lead Finish AM27S19 SA <u>/B</u> Ε e. LEAD FINISH A = Hot Solder Dip d. PACKAGE TYPE E = 16-Pin Ceramic DIP (CD 016) F = 16-Pin Flatpack (CF 016) 2 = 20-Pin Ceramic Leadless Chip Carrier (CL 020) c. DEVICE CLASS /B = Class B **b. SPEED OPTION** See Product Selector Guide a. DEVICE NUMBER/DESCRIPTION Am27S19/Am27S19A/Am27S19SA/Am27LS19 256-Bit (32 x 8) Bipolar PROM Valid Combinations Valid Combinations list configurations planned to be **Valid Combinations** supported in volume for this device. Consult the local AMD sales office to confirm availability of specific valid AM27S19 combinations or to check for newly released valid AM27S19A /BEA, /BFA, /B2A combinations. AM27S19SA AM27LS19 **Group A Tests** Group A tests consist of Subgroups 1, 2, 3, 7, 8, 9, 10, 11.

MILITARY BURN-IN

Military burn-in is in accordance with the current revision of MIL-STD-883, Test Method 1015, Conditions A through E. Test conditions are selected at AMD's option.

PIN DESCRIPTION

Au-A4 Address Inputs

The 5-bit field presented at the address inputs selects one of 32 memory locations to be read from.

Q0-Q7 Data Output Port

The outputs whose state represents the data read from the selected memory locations

G Output Enable

Provides direct control of the Q output three-state buffers. Outputs disabled forces all open-collector outputs to an

FUNCTIONAL DESCRIPTION

The Am27S19 PROM may be used as a code converter. Examples include conversion of hexadecimal, octal of BCD to seven segment display drive format. In many code conversion applications an extra PROM address input is available and may be used as a polarity control, blanking control or code OFF state and all three-state outputs to a floating or highimpedance state.

Enable = G

Disable = G

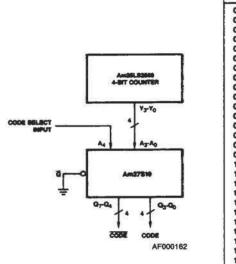
Vcc **Device Power Supply Pin** The most positive of the logic power supply pins.

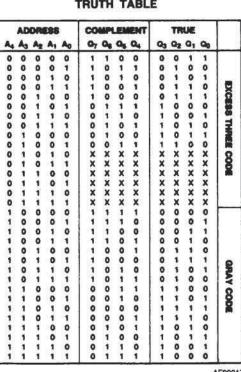
Device Power Supply Pin GND

The most negative of the logic power supply pins.

selector input. The use of a single Am27S19 to convert the outputs of a binary counter to either excess three or gray code format is illustrated below. In this case both codes are generated in true and complemented form simultaneously.

TRUTH TABLE





AF000170

ABSOLUTE MAXIMUM RATINGS

Storage Temperature 65 to + 150°
Ambient Temperature with
Power Applied 55 to + 125°
Supply Voltage 0.5 V to +7.0
DC Voltage Applied to Outputs
(Except During Programming) 0.5 to + V _{CC} Ma
DC Voltage Applied to Outputs
During Programming21
Output Current into Outputs During
Programming (Max. Duration of 1 sec.)
DC Input Voltage0.5 V to 5.5
DC Input Current 30 to +5 m

Stresses above those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to absolute maximum ratings for extended periods may affect device reliability.

OPERATING RANGES

Commercial (C) Devices	
Ambient Temperature	(T _A)0 to +75°C
Supply Voltage (V _{CC})	+4.75 V to +5.25 V
Military (M) Devices*	
Case Temperature (T	c) 55 to + 125°C
	+4.5 V to +5.5 V

Operating ranges define those limits between which the functionality of the device is guaranteed.

*Military products 100% tested at T_{C} = +25°C, +125°C, and -55°C.

DC CHARACTERISTICS	over operating ranges	s unless otherwise	specified (fo	r APL	Products,	Group A,
Subgroups 1, 2, 3 are teste	d unless otherwise no	ted)				

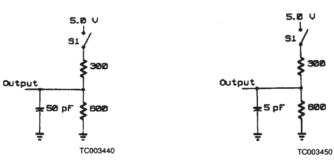
Parameter Symbol	Parameter Description	Test Conditions		Min.	Тур.	Max.	Unit	
VOH (Note 1)	Output HIGH Voltage	V _{CC} = Min., I _{OH} = -2.0 mA V _{IN} = V _{IH} or V _{IL}			2.4			v
VOL	Output LOW Voltage	V _{CC} = Min., I _{OL} = 16 mA V _{IN} = V _{IH} or V _{IL}					0.45	v
VIH	Input HIGH Level	Guaranteed input logical HIGH voltage for all inputs (Note 2)			2.0			v
VIL	Input LOW Level	Guaranteed input logical LOW voltage for all inputs (Note 2)					0.8	۷
ł <u>n</u>	Input LOW Current	V _{CC} = Max., V _{IN} = 0.45 V					-0.250	mA
IIH	Input HIGH Current	Vcc = Max., VIN = 2.7 V				100	25	μA
ISC (Note 1)	Output Short-Circuit Current	Vcc = Max., Vour = 0.0 V (Note 3)			-20		-90	mA
		Alt inputs = GND, V _{CC} = Max.		27S Devices	, i		115	mA
ICC	Power Supply Current			27LS Devices			80	100
VI	Input Clamp Voltage	V _{CC} = Min., I _{IN} = -18 mA				-1.2	۷	
		V _{CC} = Max. V _G = 2.4 V (Note 1) V _O = V _{CC} V _O = 0.4 V		Vo = Vcc	0.000	8	40	μA
CEX	Output Leakage Current			Vo = 0.4 V	_		-40	μn
CIN	Input Capacitance	V _{CC} = 5.00 V., T _A = 25°C V _{IN} /V _{OUT} = 2.0 V. @ f = 1 MHz (Note 4)			4		pF	
COUT	Output Capacitance			11.25% A168	8		P.	

Notes: 1. This applies to three-state devices only.
2. V_{IL} and V_{IH} are input conditions of output tests and are not themselves directly tested. V_{IL} and V_{IH} are absolute voltages with respect to device ground and include all overshoots due to system and/or tester noise. Do not attempt to test these values without suitable equipment.
3. Not more than one output should be shorted at a time. Duration of the short circuit should not be more than one second.
4. These parameters are not 100% tested, but are evaluated at initial characterization and at any time the design is modified where capacitance may be affected.

SWITCHING CHARACTERISTICS over operating ranges unless otherwise specified (for A	APL Products,
Group A, Subgroups 9, 10, 11 are tested unless otherwise noted*)	

				COM'L		MIL		
No.	Parameter Symbol	Parameter Description	Version	Min.	Max.	Min.	Max.	Unit
			SA		15		20	ns
		Address Valid to Output Valid Access Time	A		25		35	
1	TAVQV		STD		40		50	
			LS		55		70	
		/QZ Delay from Output Enable Valid to Output Hi-Z	SA		13		20	ns
	701/07		A		20		25	
2	TGVQZ		STD		25		30	
			LS		40		50	1
			SA		13		20	
	TOVOV	TGVQV Delay from Output Enable Valid to Output Valid	A		20		25	
з	IGVQV		STD		25		30	ns
			LS		40		50	1

See also Switching Test Circuits. Notes: 1. Tests are performed with input transition time of 5 ns or less, timing reference levels of 1.5 V, and input pulse levels of 0 to 3.0 V using test load in A under Switching Test Circuits. 2. TGVOZ is measured at steady state HIGH output voltage - 0.5 V and steady state LOW output voltage + 0.5 V output levels using the test load in B under Switching Test Circuits.



SWITCHING TEST CIRCUITS

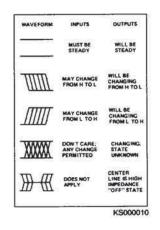
A. Output Load for all tests except TGVQZ B. Output Load for TGVQZ

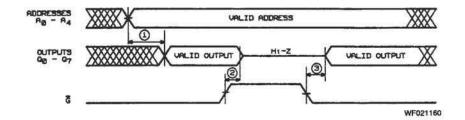
Notes: 1. All device test loads should be located within 2" of device output pin.

S₁ is open for Output Data HIGH to Hi-Z and Hi-Z to Output Data HIGH tests. S₁ is closed for all other AC tests.

3. Load capacitance includes all stray and fixture capacitance.

SWITCHING WAVEFORMS KEY TO SWITCHING WAVEFORMS





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